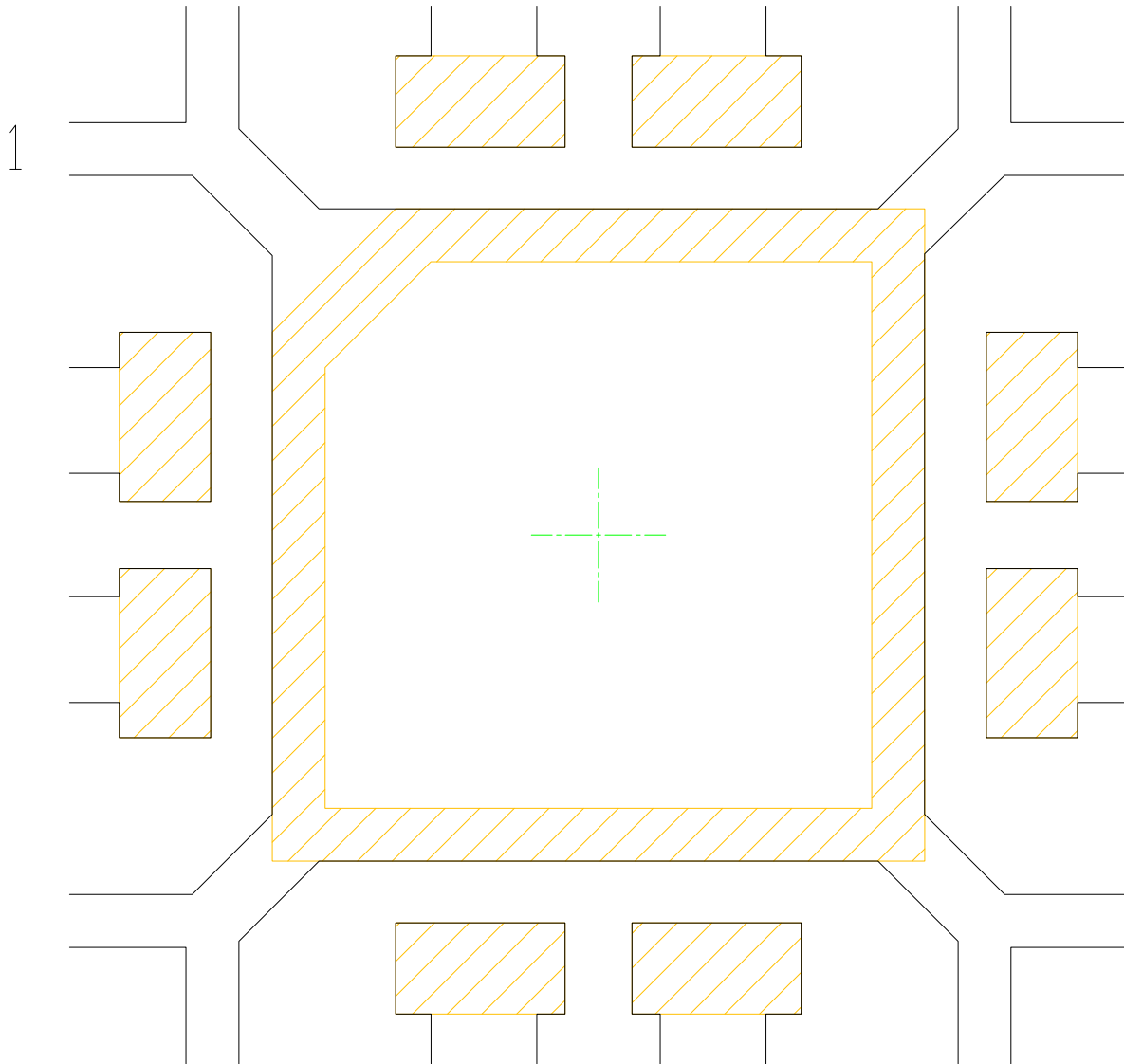



REVISIONS		
REV	DESCRIPTION	DATE
B	ADDED EXPOSED PAD SIZE AND LEADFRAME P/N	4-1-2016



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	 www.promex-ind.com	
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 1.85 x 1.85 mm		
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 1.70 x 1.70 mm	TITLE	
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING	QFN 8L 3x3 mm 0.65 PITCH BOND SHELL	
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	LEADFRAME P/N:	REV
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	235-00049	C
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	DO NOT SCALE	FILE NAME 8L-QFN-3X3-65P-BD.DWG
		SHEET	1 OF 1